

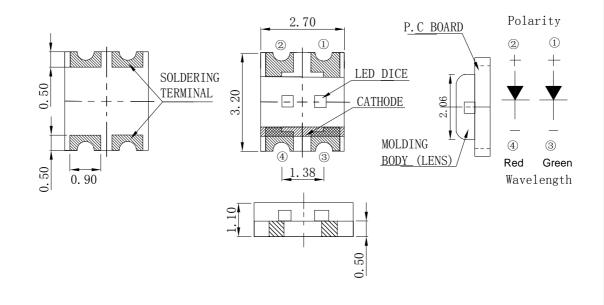
Features

- 3.2mm*2.7mm SMT LED, Super thin (1.10H mm)
- Low Power Consumption
- Wide Viewing Angle
- Various Colors
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow and wave solder process.
- Meet ROHS Green Product.
- Package: 3000pcs/Reel

Applications

• Backlight and Indicator

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.2 mm (.0079") unless otherwise noted.
- 3. Specifications are subject to change without notice
- 4. This drawing is only for reference, not as a basis for the actual structure.

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Form No : FLS0360-01 Approved By:

Rev : V.1 Prepared By: Sales@FantasyLeds.com

Page: 1 of 5 Date: 2010.5.26



FSL-3227110HGR-TCNHQ

Selection Guide

Part No	Lens Type	Dice	Emitted Color
FSL-3227110HGR-TCNHQ	Water Clear	AlInGaP	Green Red

Electrical / Optical Characteristics At Ta=25°C

Symbol	Parameter		Green	Red	Unit	Test Condition
т	Luminous Intensity	MIN.	18.0	18.0	mcd	IF=20mA
Iv		TYP.	35.0	45.0		
201/2	Viewing Angle	TYP.	130	130	deg	IF=20mA
入 Peak	Peak Emission Wavelength	TYP.	574	639	nm	IF=20mA
入d	Dominant Wavelength	TYP.	571	631	nm	IF=20mA
$ ext{ } ex ext{ } ex$	Spectral Line Half-Width	TYP.	15	20	nm	IF=20mA
VF	Forward Voltage	TYP.	2.0	2.0	V	IF=20mA
		MAX.	2.4	2.4		
IR	Reverse Current	MAX.	10	10	μA	VR 5V

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 optical centerline value

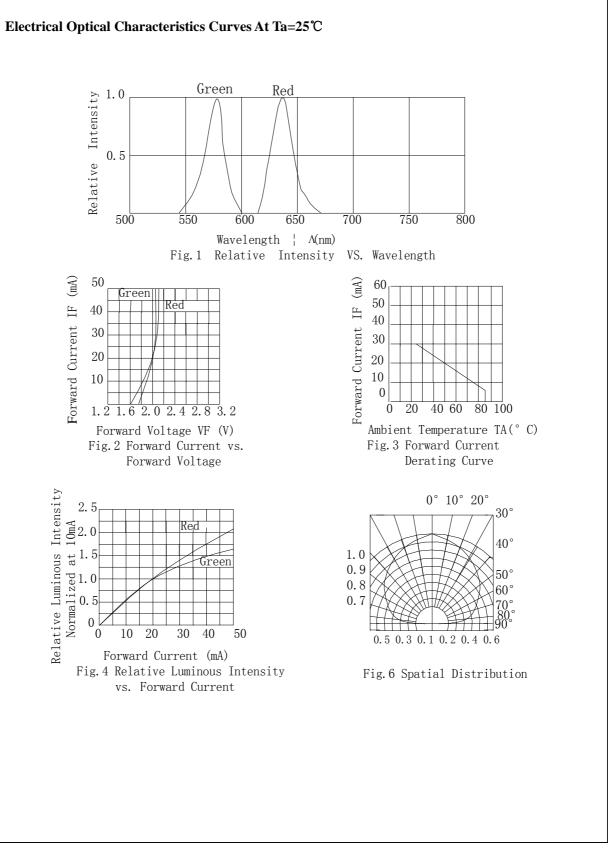
Absolute Maximum Ratings At Ta=25°C

Parameter	Green	Red	Unit		
Power Dissipation	75	75	mW		
Peak Forward Current[1]	80	80	mA		
Continuous Forward Current	30	30	mA		
Dreading Linear From30℃	0.4	0.4	mA/°C		
Reverse Voltage	5	5	V		
Operating Temperature Range	-55	-55℃ to + 85℃			
Storage Temperature Range	-55	-55℃ to + 85℃			
Soldering Condition	260°C	260°C For 5 Seconds			

Note:

1. 1/10DutyCycle, 0.1msPulseWidth

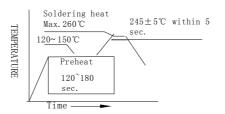






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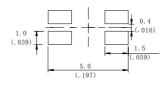
SMT Reflow Soldering Instructions



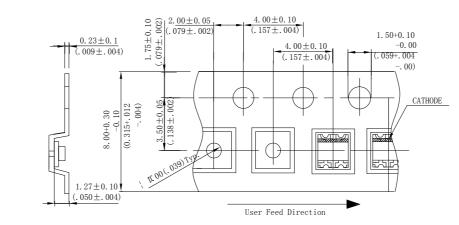
Notes:

- 1. Sells gives no other assurances regarding the ability of to withstand ESD. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.
- 2. Reflow soldering should not be done more than two times.
- 3. Do not stress LED when soldering, and do not warp the circuit board after soldering
- 4. While using Iron, Power dissipation of Iron should be smaller than 25W, and temperature should be controllable. The work should be finished within 2 sec under 320°C for once only.

Recommended Soldering Pad Dimensions



Package Specifications (Units: mm (inches))



Notes:

- 1. The LEDs should be used within a year.
- 2. The LEDs should be kept in $5 \sim 30^{\circ}$ C and 60° RH for less.
- 3. The LEDs should be used within 24 hours, or else should be kept in 5~30°C and 30% RH or less. And LEDs should be used within 7 days after opening the package.



Reliability Test Items Conditions

FSL-3227110GR-TNHQ

Classification	Test Item	Test Conditions	Test hours	Result
Endurance Test	Opertion Life	Connect with a power IF=20mA Ta=Under room temperature	- 1000Hrs	
	Hige Temperature High Humidity	Ta=+65℃±5℃ RH=90%-95%	240Hrs	0/20
	Hige Temperature Storage	High Ta= $+85^{\circ}C\pm5^{\circ}C$	1000Hrs	0/20
	Low Temperature Storage	Low Ta=-35°C±5°C Test time=1000hrs	1000Hrs	0/20
Environmental Test	Temperature Cycling	-45°C∼+105°C 15min 5min 15min	300 Cycles	0/20
	Thermal Shock	-35°C∼±5°C∼+85°C∼±5°C 5min 10sec 5min	300 Cycles	0/20
	Solder Resistance	Preheating: 120°C-150°C, within 2 minutes. Operation heating : 260°C (Max.), within 5 seconds (Max.)	5Cycles	0/20

Judgment criteria of fialure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	VF(V)	IF=20mA	Over U×1.2
Rvevrse current	Ir(µA)	Vr=5V	Over U×2
Luminous intensity	Iv(mcd)	IF=20mA	Below S×0.5

Note: 1.U means the upper limit of specified characteristics. S means initial value.

2.Meansurment shall be taken between 2 hours after the test pieces have been returned to normal ambient cnditions after completion of each test.